

Product Change Notice (PCN)

Date: 12/28/2022

PCN Number: PCN-0450904R-01

To Our Customers:

We appreciate your use of our products. Our commitment in maintaining and improving processes is demonstrated by plans to enhance our product quality, reliability, and manufacturability. The purpose of this notice is to inform you of a product change.

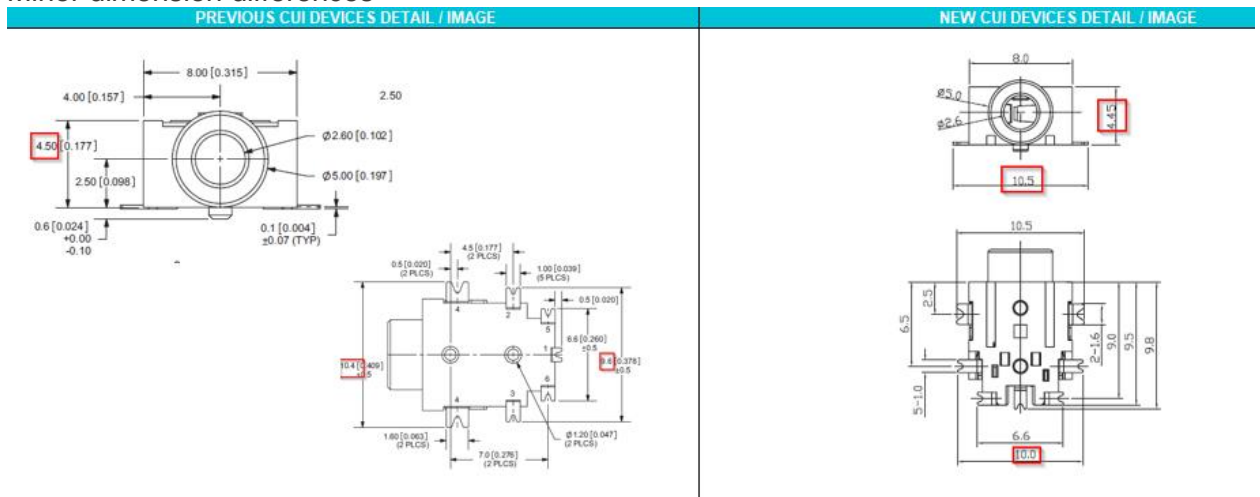
Product(s) Affected:

SJ1-42534-SMT-TR, SJ1-42535TS-SMT-TR, SJ1-42536-SMT-TR

Reason(s) for Change: *Manufacturing process improvements*

Description of Change:

1. Minor dimension differences



2. PCB pad size differs

PREVIOUS CUI DEVICES DETAIL / IMAGE	NEW CUI DEVICES DETAIL / IMAGE
<p>Recommended PCB Layout Top View</p>	<p>Recommended PCB Layout Top View</p>

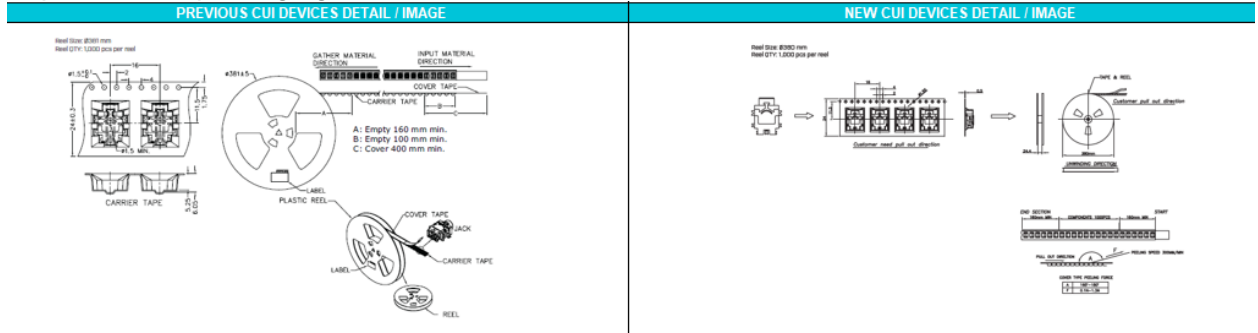
3. Housing material differs

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4. Reflow Soldering Difference

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5. Tape and reel packaging differs



Affected Date Code: **11/15/2022**

Product Availability: **Channel availability mid Q4**

Additional Information:

PCN Approval:

Operations/Quality



Product Management



Nick Wolfe 11/22/2022